

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ching Biing YEO</td> <td>06/27/2012</td> </tr> <tr> <td>Yu Gang MA</td> <td>06/27/2012</td> </tr> <tr> <td>Hisashi MASUDA</td> <td>06/27/2012</td> </tr> <tr> <td>Hirofumi KAWAMURA</td> <td>06/27/2012</td> </tr> </tbody> </table>		Name	Execution Date	Ching Biing YEO	06/27/2012	Yu Gang MA	06/27/2012	Hisashi MASUDA	06/27/2012	Hirofumi KAWAMURA	06/27/2012
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Ching Biing YEO	06/27/2012										
Yu Gang MA	06/27/2012										
Hisashi MASUDA	06/27/2012										
Hirofumi KAWAMURA	06/27/2012										
RECEIVING PARTY DATA											
Name:	SONY CORPORATION										
Street Address:	1-7-1 Konan, Minato-ku										
City:	Tokyo										
State/Country:	Japan										
Postal Code:	108-0075										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13546443</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13546443						
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Application Number:	13546443										
CORRESPONDENCE DATA											
Fax Number:	(703)413-2220										
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NAME OF SUBMITTER:	Christopher Evans										
Total Attachments: 4 source=398171USassignment#page1.tif source=398171USassignment#page2.tif source=398171USassignment#page3.tif source=398171USassignment#page4.tif											

OP \$40.00 13546443

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

A WAVEGUIDE AND METHOD FOR MAKING A WAVEGUIDE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/546, 443
Filing Date: July 11, 2012 .

This assignment executed on the dates indicated below.

Ching Biing YEO

Name of first or sole inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Yu Gang MA
Name of second inventor

27/June/2012
Execution date of U.S. Patent Application

Singapore, Singapore
Residence of second inventor

Ma Yungang
Signature of second inventor

27/June/2012
Date of this assignment

Hisashi MASUDA
Name of third inventor

Execution date of U.S. Patent Application

Singapore, Singapore
Residence of third inventor

Signature of third inventor

Date of this assignment

Hirofumi KAWAMURA
Name of fourth inventor

June 27, 2012
Execution date of U.S. Patent Application

Singapore, Singapore
Residence of fourth inventor

Hirofumi Kawamura
Signature of fourth inventor

June 27, 2012
Date of this assignment

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And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

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Ching Biing YEO
Name of first or sole inventor

27 June 2012
Execution date of U.S. Patent Application

Singapore, Singapore
Residence of first or sole inventor


Signature of first or sole inventor

27 June 2012
Date of this assignment

Yu Gang MA

Name of second inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of second inventor

Signature of second inventor

Date of this assignment

Hisashi MASUDA

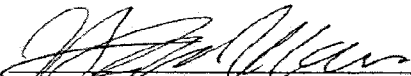
Name of third inventor

27 June 2012

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of third inventor


Signature of third inventor

27 June 2012

Date of this assignment

Hirofumi KAWAMURA

Name of fourth inventor

Execution date of U.S. Patent Application

Singapore, Singapore

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment